

Attorney Docket No.: 01CON272P

**RECEIVED  
CENTRAL FAX CENTER**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**APR 15 2004**

**OFFICIAL**

In re Application of:

**Fazelpour, Siamak**

Serial No.: 10/025,438

Filed: December 19, 2001

**For: Method for Integrating Passives On-Die  
Utilizing Under Bump Metal and  
Related Structure**

Art Unit: 2812

Examiner: Nguyen, Ha T.

**AMENDMENT AND RESPONSE TO NON-FINAL OFFICE ACTION**

Honorable Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir/Madam:

This is in response to the Non-Final Office Action dated November 24, 2003 in the above-referenced patent application. Please enter and consider the following amendments and remarks.